

CHIP CARRIER, SEMICONDUCTOR PACKAGE AND FABRICATING METHOD THEREOF

ABSTRACT

A chip carrier, a semiconductor package and a fabricating method thereof are proposed, in which on one side of the chip carrier finally removed from an engaged surface of a mold in a de-molding process there is formed at least one grounding means corresponding in position to an eject pin of the mold, so as to allow a gear amount of electrical static generated on a surface of the semiconductor package during molding and de-molding to be discharged to the outside, instead of being retained on a semiconductor chip, conductive elements and conductive traces of the semiconductor package. This therefore can prevent electrical leakage and damage to the semiconductor chip from occurrence, and improve the quality and production efficiency for the semiconductor package.

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